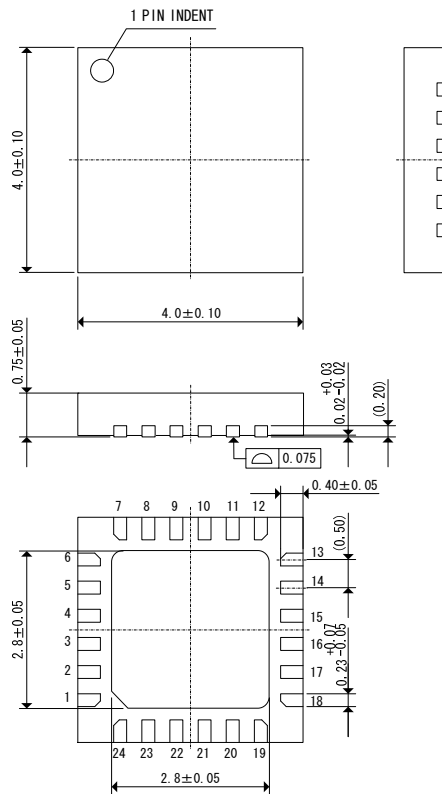


# Packaging Information / Reference Pattern Layout Dimensions

## ● QFN-24

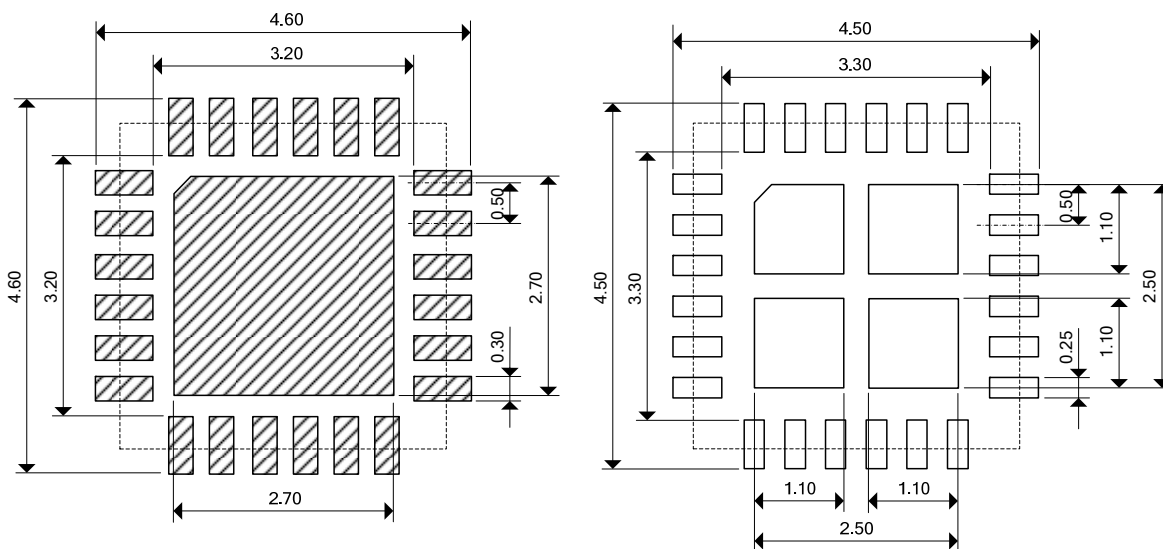
Unit: mm

### ■ Packaging Information



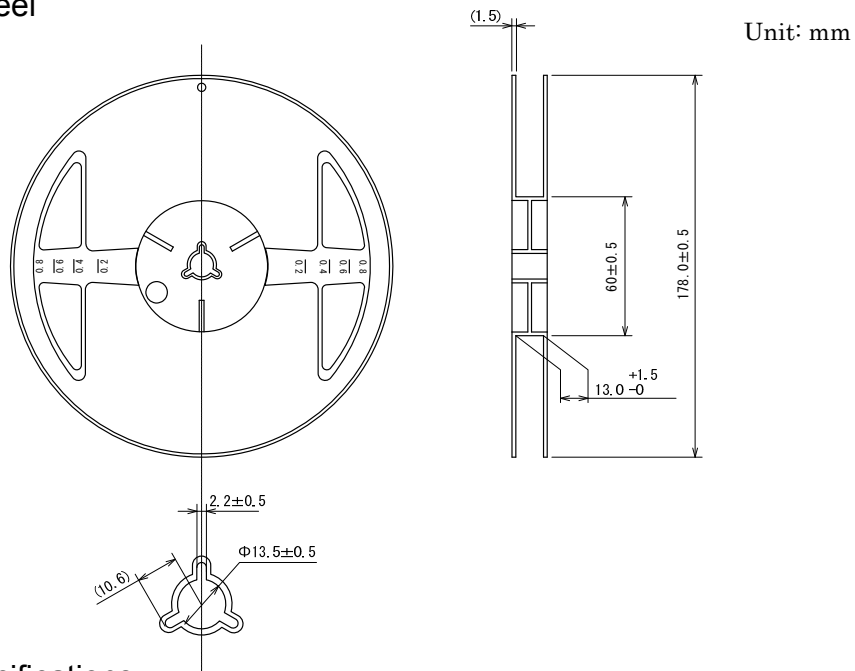
### ■ Reference Pattern Layout Dimensions

Note : reference metal mask design



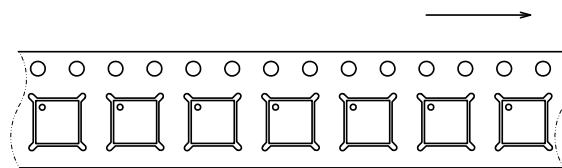
# Taping Specifications

## ●QFN-24 Reel

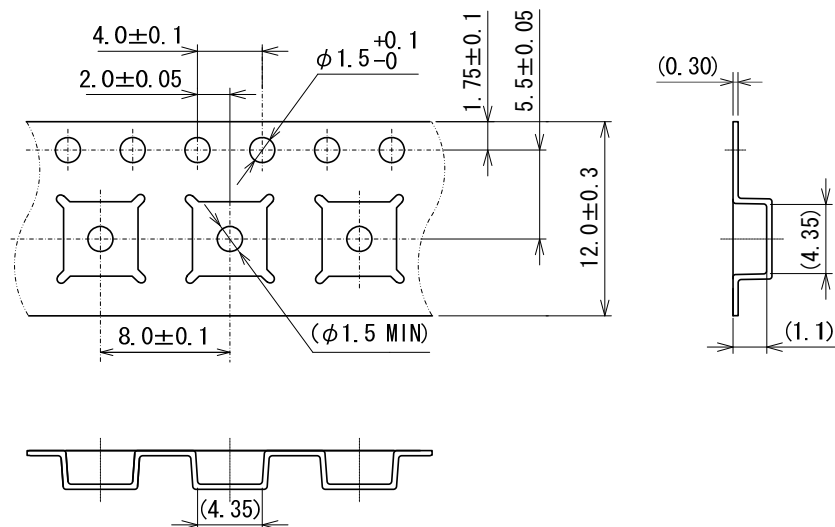


## ●Taping Specifications

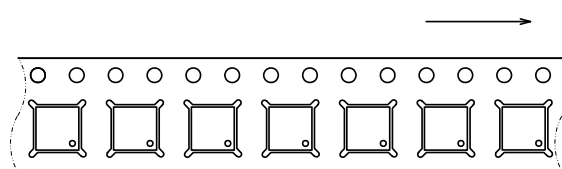
direction of feed



R Type :[Device orientation : Right] Standard feed



direction of feed



L Type :[Device orientation : Left] Reverse feed

● **QFN-24 Power Dissipation**

Power dissipation data for the QFN-24 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board Dimensions: 40 x 40 mm (1600mm<sup>2</sup>)

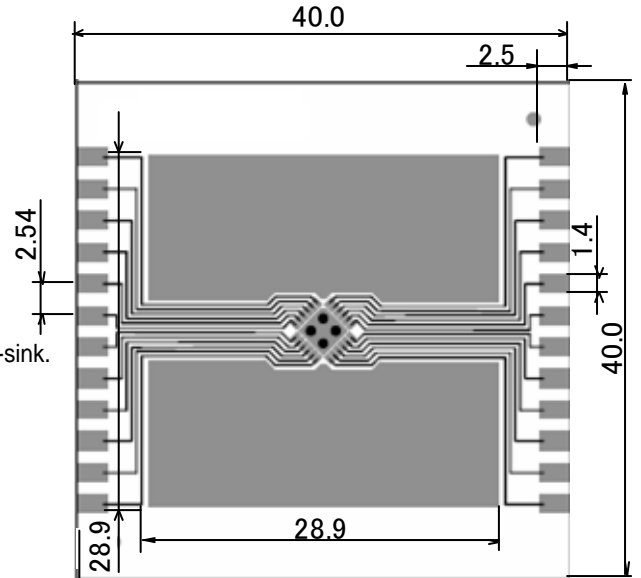
Board Structure: 4 Copper Layers

Each layer is 50% connected to the package heat-sink.

Material: Glass Epoxy (FR-4)

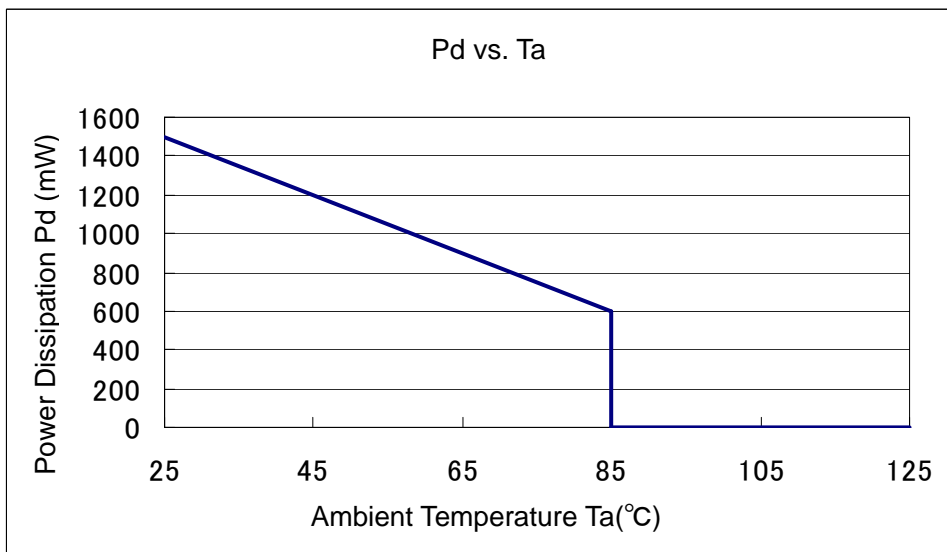
Thickness: 1.0 mm

Through-hole: 4 x 0.4 Diameter



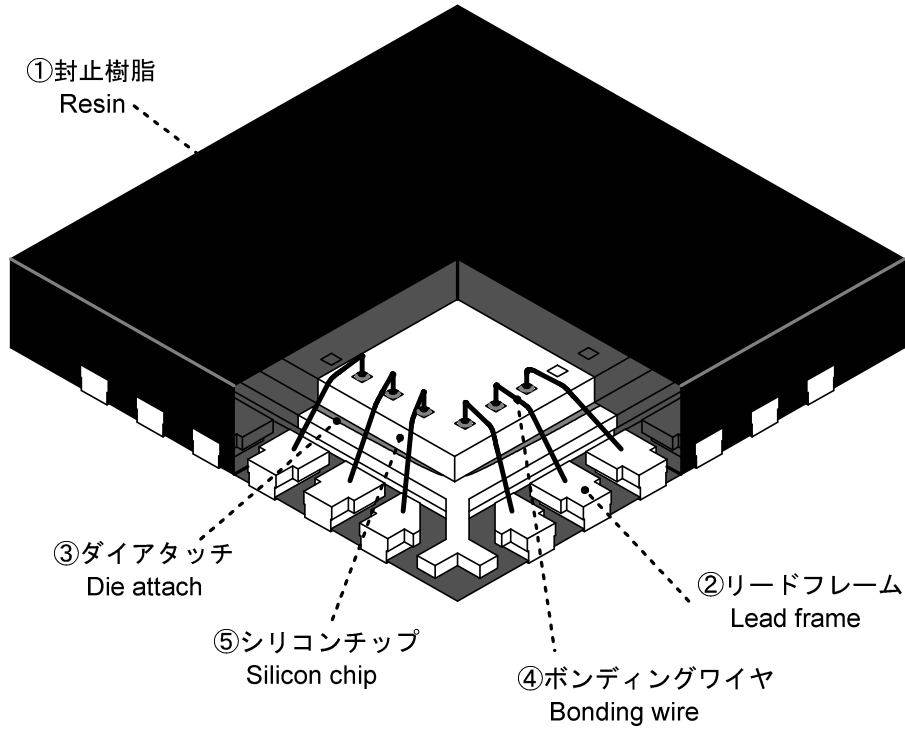
2. Power Dissipation vs. Ambient Temperature

Ambient Temperature ( °C )	Power Dissipation Pd ( mW )	Thermal Resistance(°C/W)
25	1500	66.67
85	600	



QFN-24構造図  
QFN-24 Perspective

RoHS対応品  
RoHS Compliance



項目 Item	材料 Material	備考 Note
① 封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
② リードフレーム Lead frame	銅系 Copper alloy	
端子処理 Lead plating	鉛フリーはんだメッキ Lead(Pb) free solder plating	端子側面は除く Except the side of the terminals.
③ ダイアタッチ Die attach	エポキシ Epoxy	
④ ボンディングワイヤ Bonding wire	Au	
⑤ シリコンチップ Silicon chip	Si	

捺印表示 Marking	レーザー Laser marking
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